

FEATURES

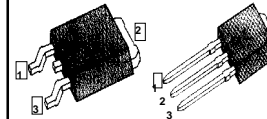
- ◆ Avalanche Rugged Technology
- ◆ Rugged Gate Oxide Technology
- ◆ Lower Input Capacitance
- ◆ Improved Gate Charge
- ◆ Extended Safe Operating Area
- ◆ 150°C Operating Temperature
- ◆ Lower Leakage Current: 10µA (Max.) @ $V_{DS} = 200V$
- ◆ Lower $R_{DS(ON)}$: 0.145Ω (Typ.)

$$BV_{DSS} = 200 V$$

$$R_{DS(on)} = 0.18\Omega$$

$$I_D = 18 A$$

D²-PAK I²-PAK



1. Gate 2. Drain 3. Source

Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
V_{DSS}	Drain-to-Source Voltage	200	V
I_D	Continuous Drain Current ($T_C=25^\circ C$)	18	A
	Continuous Drain Current ($T_C=100^\circ C$)	11.4	
I_{DM}	Drain Current-Pulsed (1)	63	A
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulsed Avalanche Energy (2)	64	mJ
I_{AR}	Avalanche Current (1)	18	A
E_{AR}	Repetitive Avalanche Energy (1)	11	mJ
dv/dt	Peak Diode Recovery dv/dt (3)	5	V/ns
P_D	Total Power Dissipation ($T_A=25^\circ C$) *	3.1	W
	Total Power Dissipation ($T_C=25^\circ C$)	110	W
	Linear Derating Factor	0.88	W/ $^\circ C$
T_J, T_{STG}	Operating Junction and Storage Temperature Range	- 55 to +150	$^\circ C$
T_L	Maximum Lead Temp. for Soldering Purposes, 1/8. from case for 5-seconds	300	

Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	--	1.14	$^\circ C/W$
$R_{\theta JA}$	Junction-to-Ambient *	--	40	
$R_{\theta JA}$	Junction-to-Ambient	--	62.5	

* When mounted on the minimum pad size recommended (PCB Mount).

Rev. B

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
BV_{DSS}	Drain-Source Breakdown Voltage	200	--	--	V	$V_{GS}=0V, I_D=250\mu\text{A}$
$\Delta BV/\Delta T_J$	Breakdown Voltage Temp. Coeff.	--	0.17	--	V/ $^\circ\text{C}$	$I_D=250\mu\text{A}$ See Fig 7
$V_{GS(th)}$	Gate Threshold Voltage	1.0	--	2.0	V	$V_{DS}=5V, I_D=250\mu\text{A}$
I_{GSS}	Gate-Source Leakage, Forward	--	--	100	nA	$V_{GS}=20V$
	Gate-Source Leakage, Reverse	--	--	-100		$V_{GS}=-20V$
I_{DSS}	Drain-to-Source Leakage Current	--	--	10	μA	$V_{DS}=200V$
		--	--	100		$V_{DS}=160V, T_C=125^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-State Resistance	--	--	0.18	Ω	$V_{GS}=5V, I_D=9A$ (4)
g_{fs}	Forward Transconductance	--	13.3	--	\bar{U}	$V_{DS}=40V, I_D=9A$ (4)
C_{iss}	Input Capacitance	--	1310	1705	pF	$V_{GS}=0V, V_{DS}=25V, f=1\text{MHz}$ See Fig 5
C_{oss}	Output Capacitance	--	200	250		
C_{rss}	Reverse Transfer Capacitance	--	95	120		
$t_{d(on)}$	Turn-On Delay Time	--	11	30	ns	$V_{DD}=100V, I_D=18A,$ $R_G=4.6\Omega$ See Fig 13 (4) (5)
t_r	Rise Time	--	8	25		
$t_{d(off)}$	Turn-Off Delay Time	--	46	100		
t_f	Fall Time	--	15	40		
Q_g	Total Gate Charge	--	40	56	nC	$V_{DS}=160V, V_{GS}=5V,$ $I_D=18A$ See Fig 6 & Fig 12 (4) (5)
Q_{gs}	Gate-Source Charge	--	6.8	--		
Q_{gd}	Gate-Drain(. Miller.) Charge	--	18.6	--		

Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
I_S	Continuous Source Current	--	--	18	A	Integral reverse pn-diode in the MOSFET
I_{SM}	Pulsed-Source Current (1)	--	--	63		
V_{SD}	Diode Forward Voltage (4)	--	--	1.5	V	$T_J=25^\circ\text{C}, I_S=18A, V_{GS}=0V$
t_{rr}	Reverse Recovery Time	--	224	--	ns	$T_J=25^\circ\text{C}, I_F=18A$
Q_{rr}	Reverse Recovery Charge	--	1.55	--	μC	$di_F/dt=100A/\mu\text{s}$ (4)

Notes;

- (1) Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
- (2) $L=0.3\text{mH}, I_{AS}=18A, V_{DD}=50V, R_G=27\Omega$, Starting $T_J=25^\circ\text{C}$
- (3) $I_{SD} \leq 18A, di/dt \leq 260A/\mu\text{s}, V_{DD} \leq BV_{DSS}$, Starting $T_J=25^\circ\text{C}$
- (4) Pulse Test: Pulse Width = 250 μs , Duty Cycle $\leq 2\%$
- (5) Essentially Independent of Operating Temperature

Fig 1. Output Characteristics

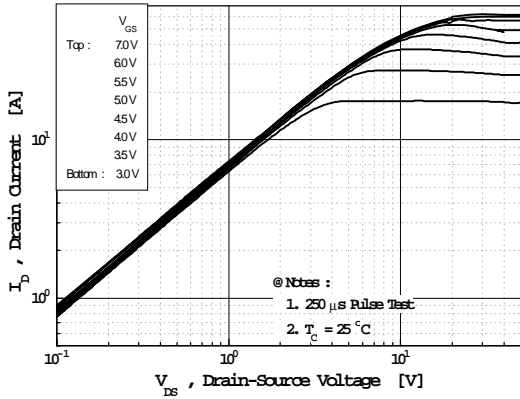


Fig 2. Transfer Characteristics

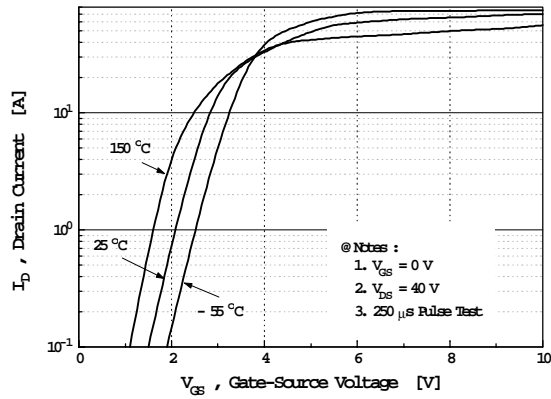


Fig 3. On-Resistance vs. Drain Current

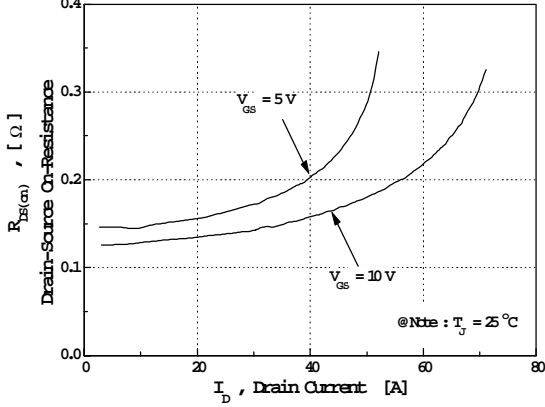


Fig 4. Source-Drain Diode Forward Voltage

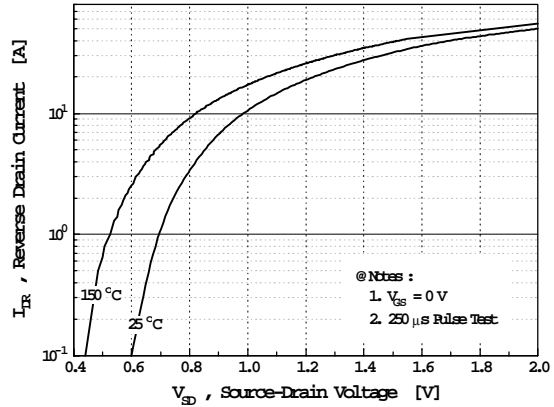


Fig 5. Capacitance vs. Drain-Source Voltage

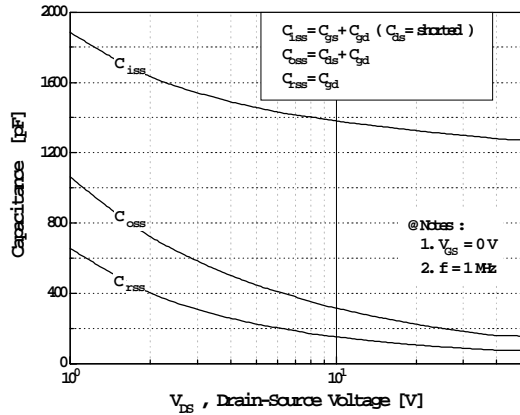


Fig 6. Gate Charge vs. Gate-Source Voltage

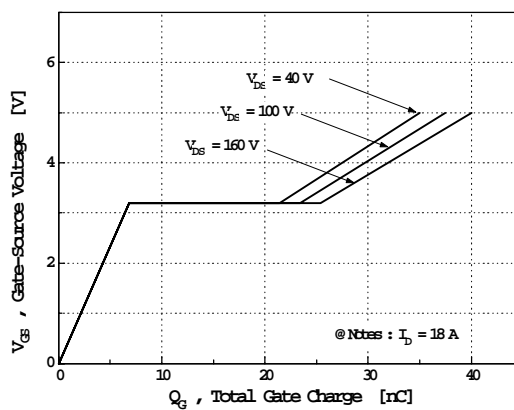


Fig 7. Breakdown Voltage vs. Temperature

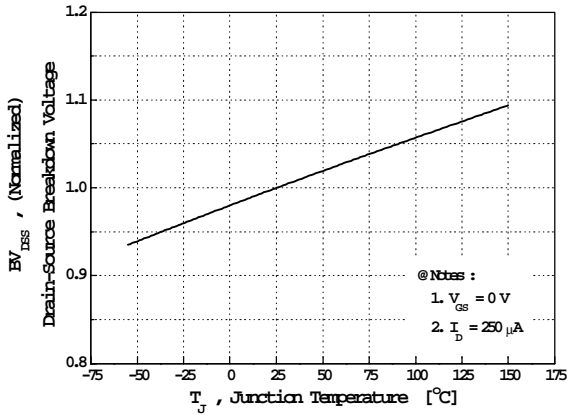


Fig 8. On-Resistance vs. Temperature

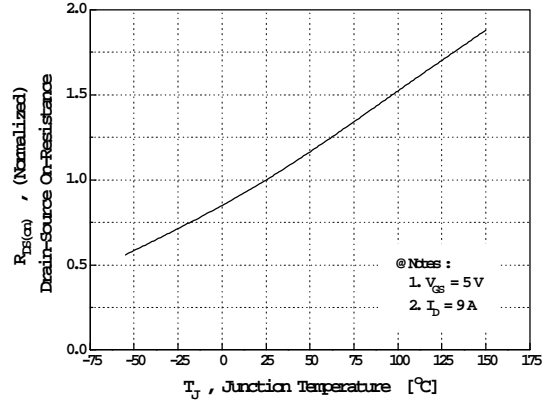


Fig 9. Max. Safe Operating Area

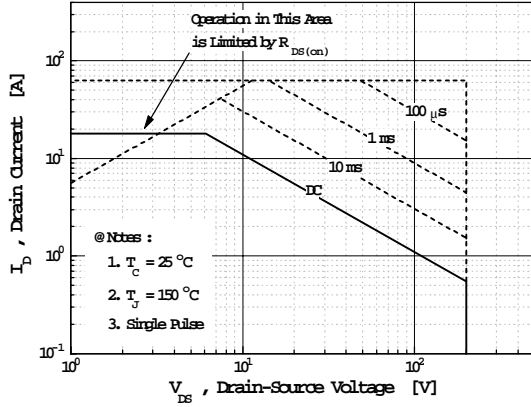


Fig 10. Max. Drain Current vs. Case Temperature

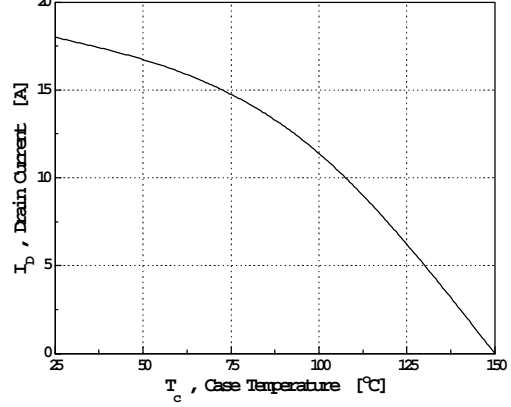


Fig 11. Thermal Response

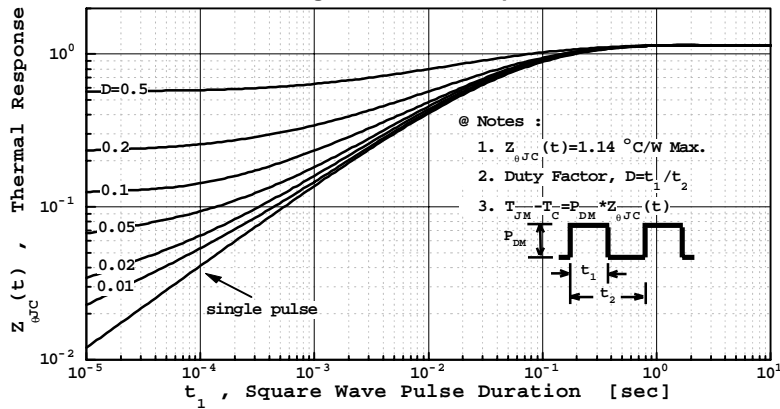


Fig 12. Gate Charge Test Circuit & Waveform

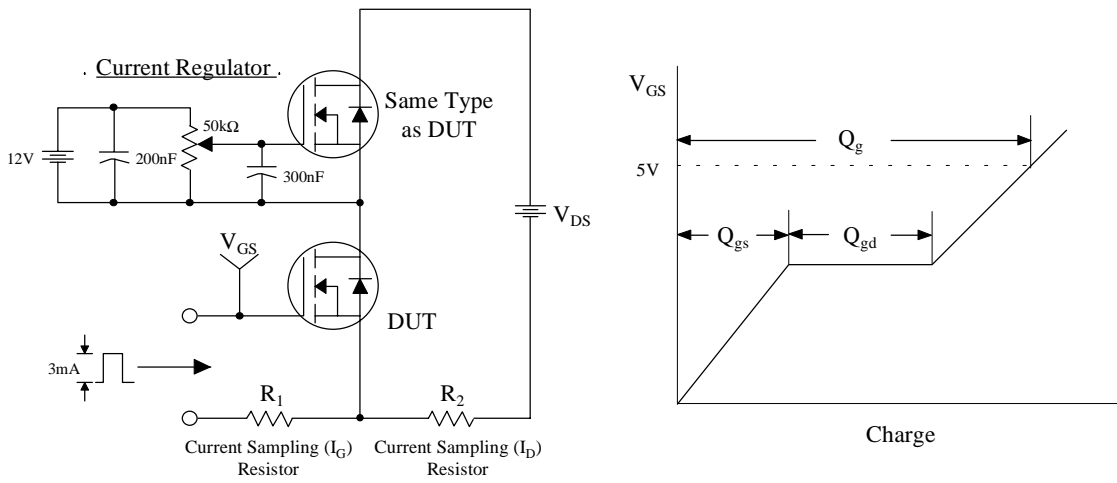


Fig 13. Resistive Switching Test Circuit & Waveforms

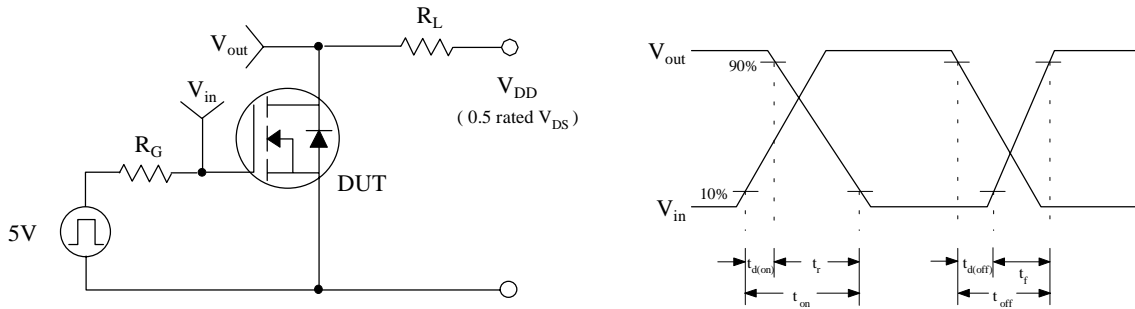


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

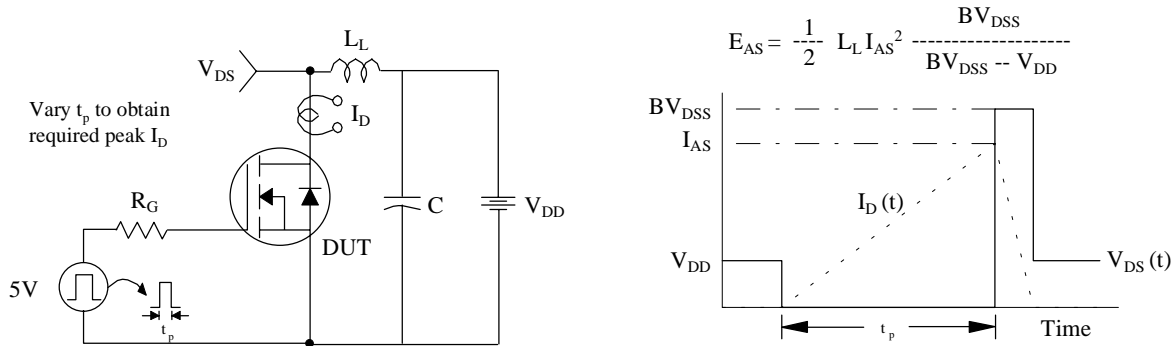
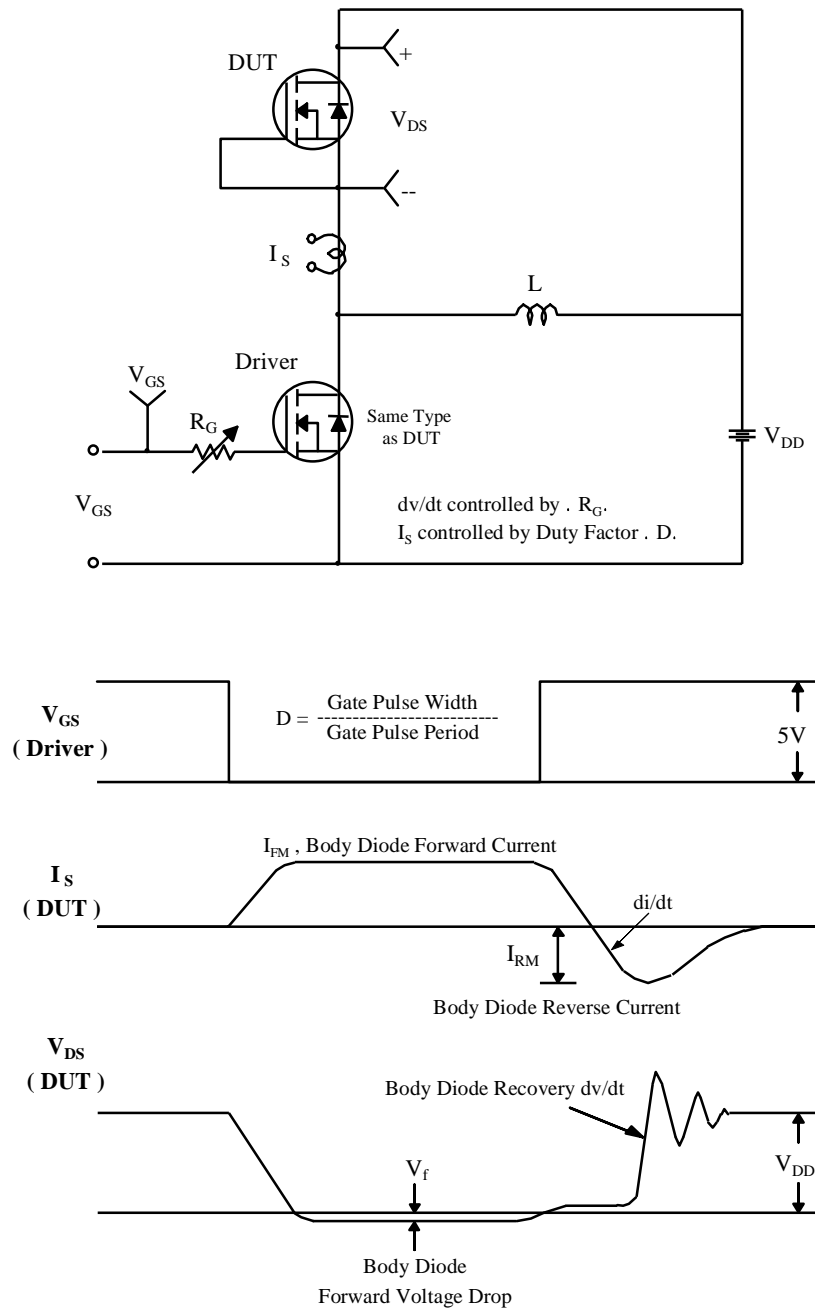


Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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